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8-bit Register/Binary Counter



ADE-205-513 (Z) 1st. Edition Sep. 2000

Description

The HD74HC592 consists of a parallel input, 8-bit storage register feeding an 8-bit binary counter. Both the register and the counter have individual positive edge-triggered clocks. In addition, the counter has direct load and clear functions. Expansion is easily accomplished by connecting $\overline{\text{RCO}}$ of the first stage to the count enable of the second stage, etc.

Features

• High Speed Operation: t_{pd} (CCK to \overline{RCO}) = 24 ns typ (C_L = 50 pF)

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2$ to 6 V

• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

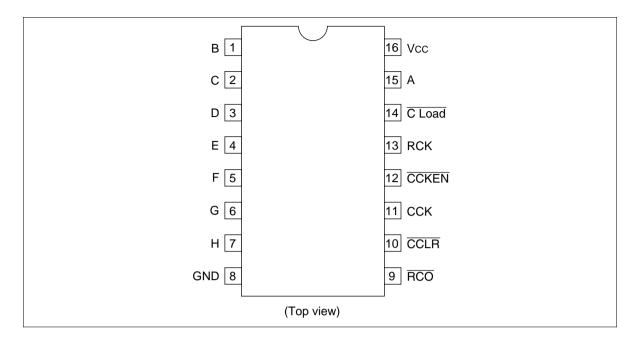
Function Table

Inputs

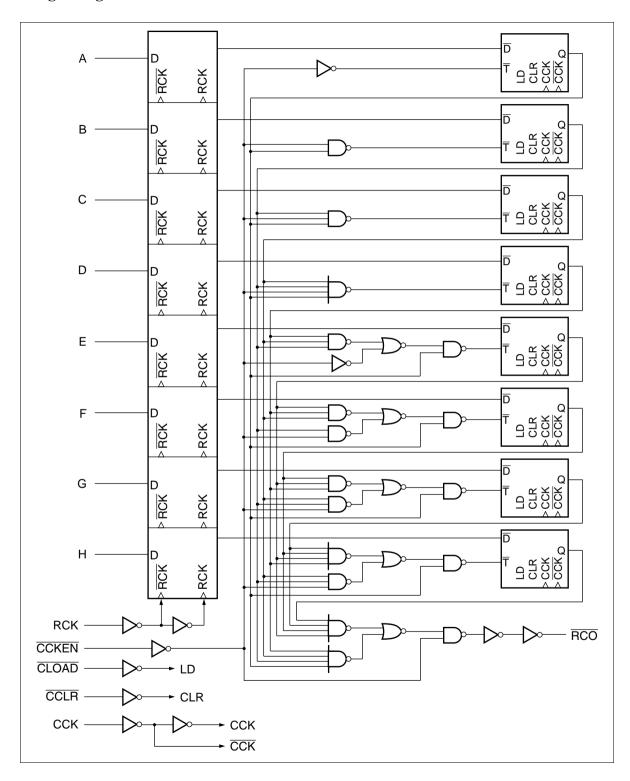
RCK	CLoad	CCLR	CCKEN	ССК	Function				
X	L	Н	Х	Χ	Regiater data loaded into counter				
X	Н	L	Х	Х	Counter clear				
$\overline{\int}$	Н	Н	Х	Х	Input data A to H stored into register				
$\overline{}$	Н	Н	Х	Х	No change in register				
Х	Н	Н	L		Count up				
X	Н	Н	L		No count				
X	Н	Н	Н	Х	No cont				

 $\overline{RCO} = QA' \bullet QB' \bullet QC' \bullet QD' \bullet QE' \bullet QF' \bullet QG' \bullet QH' \bullet \overline{(\overline{CCKEN})} \ (QA' \ to \ QH': \ Output \ of \ Internal \ Counter)$

Pin Arrangement



Logic Diagram



DC Characteristics

			Ta = 25°C		+85°C				
Item	Symbol	V_{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Input voltage	V_{IH}	2.0	1.5	_	_	1.5	_	V	
		4.5	3.15	_	_	3.15	_	_	
		6.0	4.2	_	_	4.2	_	=	
	V _{IL}	2.0	_	_	0.5	_	0.5	V	
		4.5		_	1.35	_	1.35	_	
		6.0	_	_	1.8	_	1.8	=	
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	Vin = V_{IH} or V_{IL} I_{OH} = $-20 \mu A$
		4.5	4.4	4.5	_	4.4	_	_	
		6.0	5.9	6.0	_	5.9	_	_	
		4.5	4.18	_	_	4.13	_	_	$I_{OH} = -4 \text{ mA}$
		6.0	5.68	_	_	5.63	_	_	$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	Vin = V_{IH} or V_{IL} I_{OL} = 20 μA
		4.5	_	0.0	0.1	_	0.1	_	
		6.0	_	0.0	0.1	_	0.1	_	
		4.5	_	_	0.26	_	0.33	_	$I_{OL} = 4 \text{ mA}$
		6.0	_	_	0.26	_	0.33	_	$I_{OL} = 5.2 \text{ mA}$
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GND
Quiescent supply current	I _{cc}	6.0	_	_	4.0	_	40	μΑ	Vin = V_{CC} or GND, lout = $0 \mu A$

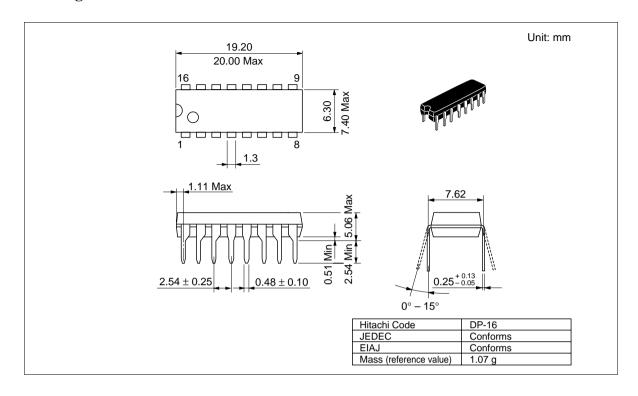
Ta = -40 to

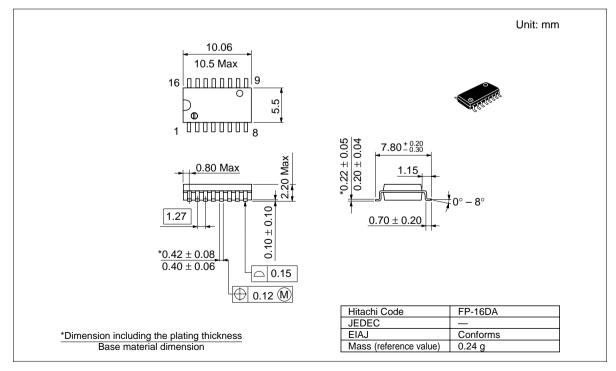
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Ta = -40 to $Ta = 25^{\circ}C$ +85°C

Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	f _{max}	2.0	_	_	5	_	4	MHz	
frequency		4.5	_	_	25	_	20	_	
		6.0	_	_	29	_	24	_	
Propagation delay	t _{PLH}	2.0	_	_	200	_	250	ns	CCK to RCO
time	$t_{\tiny PHL}$	4.5	_	24	40	_	50	=	
		6.0	_	_	34	_	43	=	
	t _{PLH}	2.0	_	_	200	_	250	ns	C Load to RCO
	$t_{\tiny PHL}$	4.5	_	27	40	_	50		
		6.0	_	_	34	_	43		
	t _{PLH}	2.0	_	_	200	_	250	ns	CCLR to RCO
		4.5	_	26	40	_	50	=	
		6.0	_	_	34	_	43	=	
	t _{PLH}	2.0	_	_	300	_	375	ns	RCK to RCO
	$t_{\tiny PHL}$	4.5	_	29	60	_	75	=	
		6.0	_	_	51	_	64	=	
Pulse width	t _w	2.0	80	_	_	100	_	ns	
		4.5	16	8	-	20	_	_	
		6.0	14	_	_	17	_		
Removal time	t _{rem}	2.0	100	_	_	125	_	ns	CCLR to CCK
		4.5	20	12	_	25	_	_	
		6.0	17	_	_	21	_		
Setup time	t _{su}	2.0	100	_	_	125	_	ns	CCKEN to CCK
		4.5	20	0	_	25	_		
		6.0	17	_	_	21	_		
		2.0	200	_	_	250	_	ns	CCK to RCK
		4.5	40	14		50	_		
		6.0	34	_		43	_		
Output rise/fall	t _{TLH}	2.0	_	_	75	_	95	ns	
time	\mathbf{t}_{THL}	4.5	_	5	15	_	19		
		6.0	_	_	13	_	16		
Input capacitance	Cin	_	_	5	10	_	10	pF	

Package Dimensions





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